

TPS3809x 3 引脚电源电压监控器

1 特性

- 3 引脚 SOT-23 封装
- 电源电流为 9 μ A (典型值)
- 精密电源电压监控器：
2.5V、3V、3.3V、5V
- 与 MAX 809 引脚对引脚兼容
- 温度范围：-40°C 至 +85°C

2 应用

- 工厂自动化
- 无线音箱
- 电机驱动器
- 服务器
- 电器
- 电表
- 楼宇自动化

3 说明

TPS3809 系列监控电路主要为 DSP 及基于处理器的系统提供电路初始化和计时监控功能。新款 TLV809E 器件是具有相同引脚、功能和电气参数的替代产品。

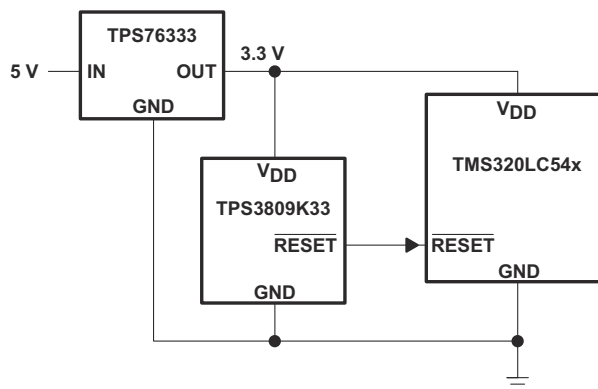
上电期间，如果电源电压 V_{DD} 大于 1.1V， \overline{RESET} 就会生效。因此，只要 V_{DD} 保持在阈值电压 V_{IT} 以下，监控电路就会监测 V_{DD} ，并使 \overline{RESET} 保持有效状态。内部计时器将会延迟输出恢复至无效状态（高电平）的时间，以确保系统正常复位。延时时间 $t_{d(typ)} = 200ms$ ，从 V_{DD} 上升至高于阈值电压 V_{IT} 后开始计时。电源电压降至阈值电压 V_{IT} 以下时，输出再次变为有效状态（低电平）。无需外部组件。该系列所有器件均具有由内部分压器设定的固定检测阈值电压 V_{IT} 。

该产品系列旨在用于 2.5V、3V、3.3V 和 5V 电源电压。这些电路都采用 3 引脚 SOT-23 封装。TPS3809 器件的工作温度范围为 -40°C 至 +85°C。

器件信息

器件型号	封装 (1)	封装尺寸 (标称值)
TPS3809	SOT-23 (3)、DBV	2.90mm × 1.60mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



典型应用



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4 Revision History

Changes from Revision C (October 2013) to Revision D (January 2021)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• 在说明部分添加了有关新款 TLV809E 的描述.....	1
• Added the pinout and pin function table.....	4
• Changed VDD from 7 to 6.5 in <i>Absolute Maximum Ratings</i>	5
• Changed V_{OL} @ 500 μ A from 0.2 to 0.3V and corrected header of the table from TPS3800-xx, TPS3801-xx, TPS3802-xx to TPS3809xx in <i>Electrical Characteristics</i>	5
• Changed t_w pulse duration from 3 to 10 μ s in <i>Timing Requirements</i>	6
• Changed t_{PHL} from 1 to 10 μ s in <i>Switching Characteristics</i>	6
Changes from Revision B (July 2012) to Revision C (October 2013)	Page
• 更改了首页和页面流程，以便匹配当前标准外观.....	1
• Changed "Operating junction temperature range" to "Operating free-air temperature range" in Absolute Maximum Ratings (typo).....	5
Changes from Revision A (October 2010) to Revision B (July 2012)	Page
• Changed the Pull-up resistor value, \overline{RESET} To: \overline{RESET} current sink during startup in the Recommended Operating Conditions Table.....	5
Changes from Revision * (August 1999) to Revision A (October 2010)	Page
• Added Pull-up resistor value, \overline{RESET} to the Recommended Operating Conditions Table.....	5

5 Device Comparison

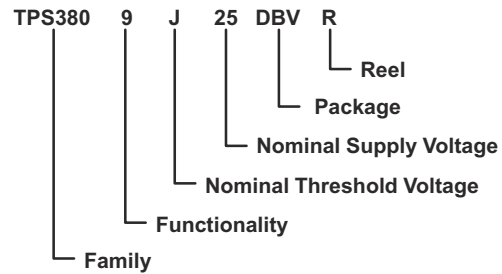
表 5-1. Device Comparison Table

T _A	DEVICE NAME		THRESHOLD VOLTAGE	MARKING
- 40°C to 85°C	TPS3809J25DBVR	TPS3809J25DBVT	2.25 V	PCZI
	TPS3809L30DBVR	TPS3809L30DBVT	2.64 V	PDAI
	TPS3809K33DBVR	TPS3809K33DBVT	2.93 V	PDBI
	TPS3809I50DBVR	TPS3809I50DBVT	4.55 V	PDCI

FUNCTION/TRUTH TABLE, TPS3809

V _{DD} >V _{IT}	$\overline{\text{RESET}}$
0	L
1	H

ORDERING INFORMATION



6 Pin Configuration and Functions

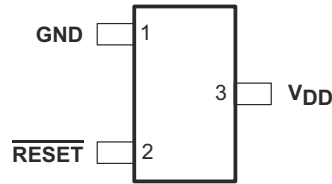


图 6-1. Pin configuration

表 6-1. Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION
NAME	NO.		
GND	1	-	This pin should be connected to ground with a low-impedance connection.
RESET	2	O	RESET is an active low signal, asserting when V _{DD} is below the threshold voltage. When V _{DD} rises above V _{IT} , there is a delay time (t _d) until RESET deasserts. RESET is a push-pull output stage.
VDD	3	-	Supply voltage pin. A 0.1-μF ceramic capacitor from this pin to ground is recommended to improve stability of the threshold voltage

7 Specifications

7.1 Absolute Maximum Ratings ⁽¹⁾ ⁽²⁾

Over operating free-air temperature range (unless otherwise noted).

	UNIT
Supply voltage, V_{DD}	6.5 V
All other pins	- 0.3 V to 6.5 V
Maximum low-output current, I_{OL}	5 mA
Maximum high-output current, I_{OH}	- 5 mA
Input-clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	± 20 mA
Output-clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	± 20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	- 40°C to 85°C
Storage temperature range, T_{stg}	- 65°C to 150°C

- Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- All voltage values are with respect to GND. For reliable operation, the device should not be operated at 6.5 V for more than $t = 1000$ h continuously.

7.2 Recommended Operating Conditions

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
RESET current sink during startup		50	μ A
Operating free-air temperature range, T_A	- 40	+85	°C

7.3 Dissipation Ratings

PACKAGE	$T_A < 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A < 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

7.4 Electrical Characteristics

Over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER	TEST CONDITIONS	TPS3809xx			UNIT
		MIN	TYP	MAX	
V_{OH} High-level output voltage	$V_{DD} = 2.5$ V to 6 V $I_{OH} = - 500$ μ A	$V_{DD} - 0.2$			V
	$V_{DD} = 3.3$ V $I_{OH} = - 2$ mA	$V_{DD} - 0.4$			
	$V_{DD} = 6$ V $I_{OH} = - 4$ mA	$V_{DD} - 0.4$			
V_{OL} Low-level output voltage	$V_{DD} = 2$ V to 6 V, $I_{OL} = 500$ μ A			0.3	V
	$V_{DD} = 3.3$ V, $I_{OL} = 2$ mA			0.4	
	$V_{DD} = 6$ V, $I_{OL} = 4$ mA			0.4	
Power-up reset voltage ⁽¹⁾	$V_{DD} \geq 1.1$ V, $I_{OL} = 50$ μ A			0.2	V
V_{IT} - Negative-going input threshold voltage ⁽²⁾	TPS3809J25	2.2	2.25	2.3	V
	TPS3809L30	2.58	2.64	2.7	
	TPS3809K33	2.87	2.93	2.99	
	TPS3809I50	4.45	4.55	4.65	
V_{hys} Threshold hysteresis	TPS3809J25		30		mV
	TPS3809L30		35		
	TPS3809K33		40		
	TPS3809I50		60		

Over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER		TEST CONDITIONS	TPS3809xx			UNIT
			MIN	TYP	MAX	
I _{DD}	Supply current	V _{DD} = 2 V, output unconnected		9	12	μ A
		V _{DD} = 6 V, output unconnected		20	25	
C _i	Input capacitance	V _I = 0 V to V _{DD}		5		pF

- (1) The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. $t_{r, V_{DD}} \geq 15 \mu\text{s/V}$.
- (2) To ensure the best stability of the threshold voltage, a bypass capacitor (0.1-μ F ceramic) should be placed near the supply terminals.

7.5 Timing Requirements

at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

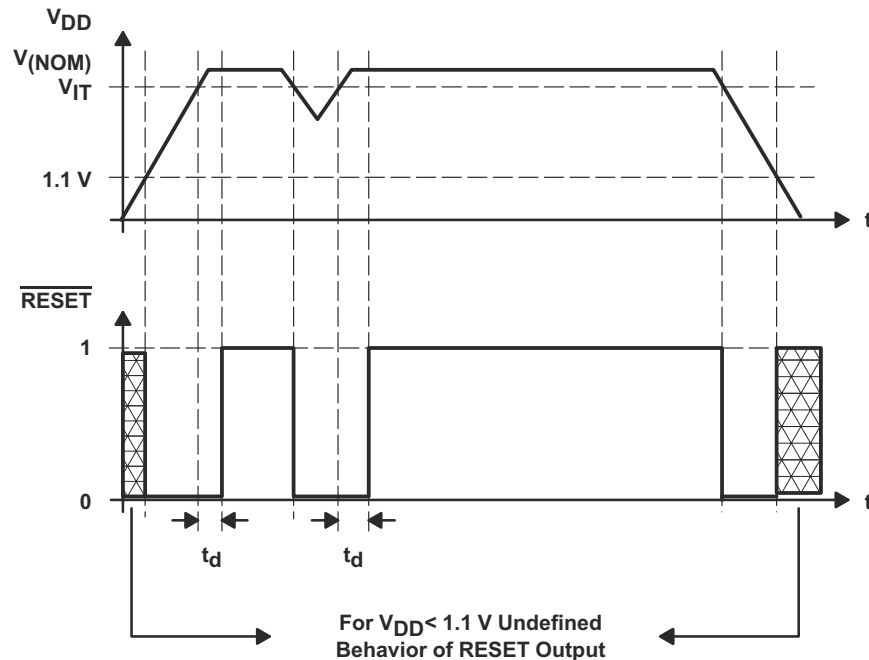
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t _w	Pulse width	at V _{DD}	V _{DD} = V _{IT-} + 0.2 V, V _{DD} = V _{IT-} - 0.2 V			10	μ s

7.6 Switching Characteristics

at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _d	Delay time	V _{DD} ≥ V _{IT-} + 0.2 V, See timing diagram	120	200	280	ms
t _{PHL}	Propagation (delay) time, high-to-low-level output	V _{DD} to $\overline{\text{RESET}}$ delay V _{IL} = V _{IT-} - 0.2 V, V _{IH} = V _{IT-} + 0.2 V		10		μ s

7.7 Timing Diagram



7.8 Typical Characteristics

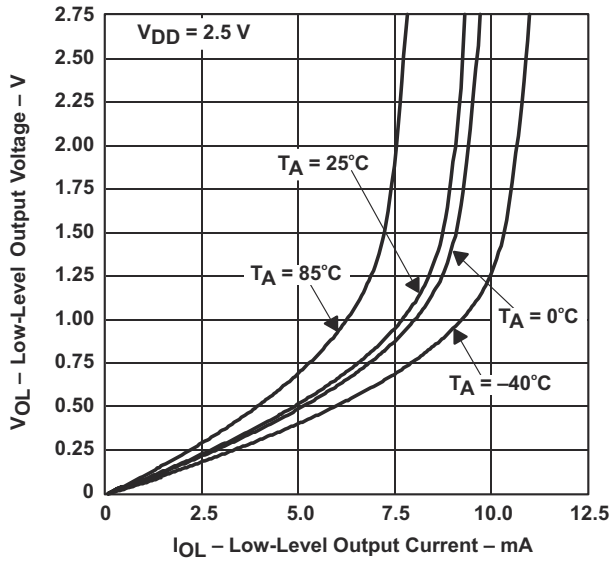


图 7-1. LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

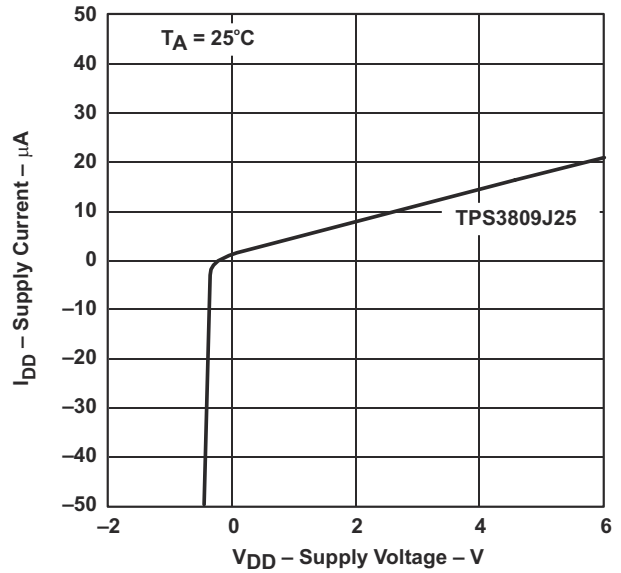


图 7-2. SUPPLY CURRENT vs SUPPLY VOLTAGE

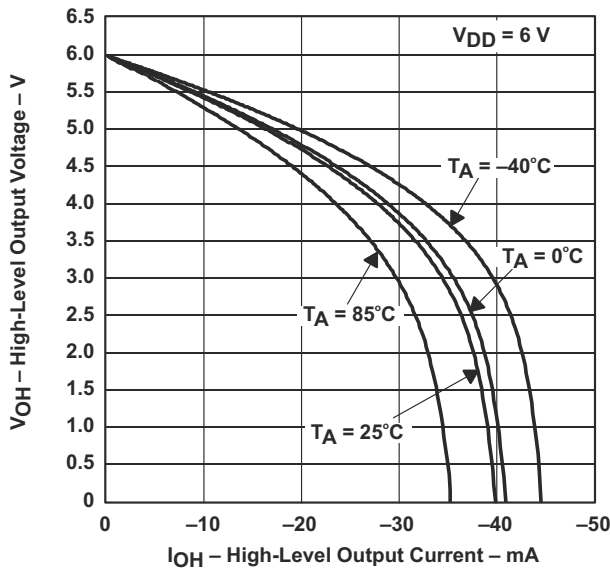


图 7-3. HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT at $V_{DD}=6V$

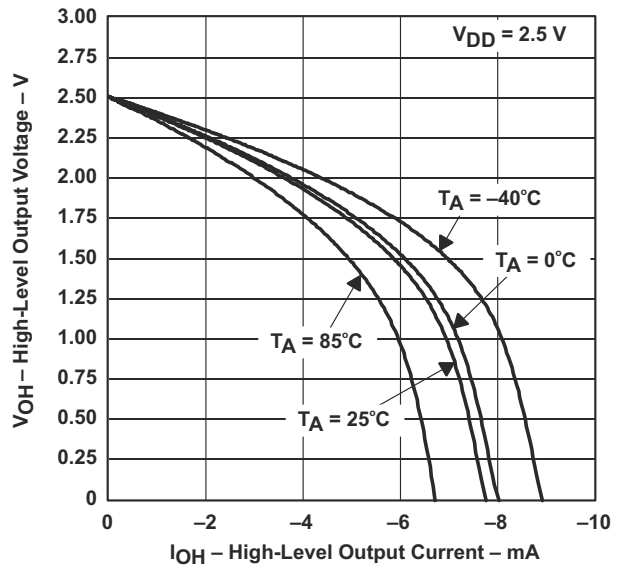


图 7-4. HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT at $V_{DD}=2.5V$

7.8 Typical Characteristics (continued)

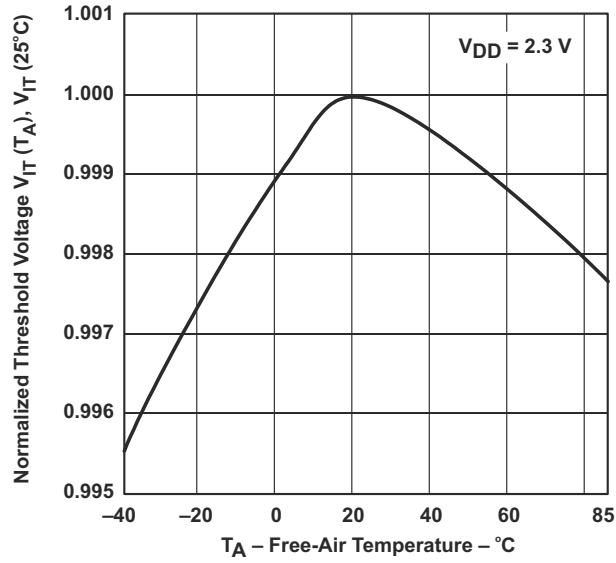
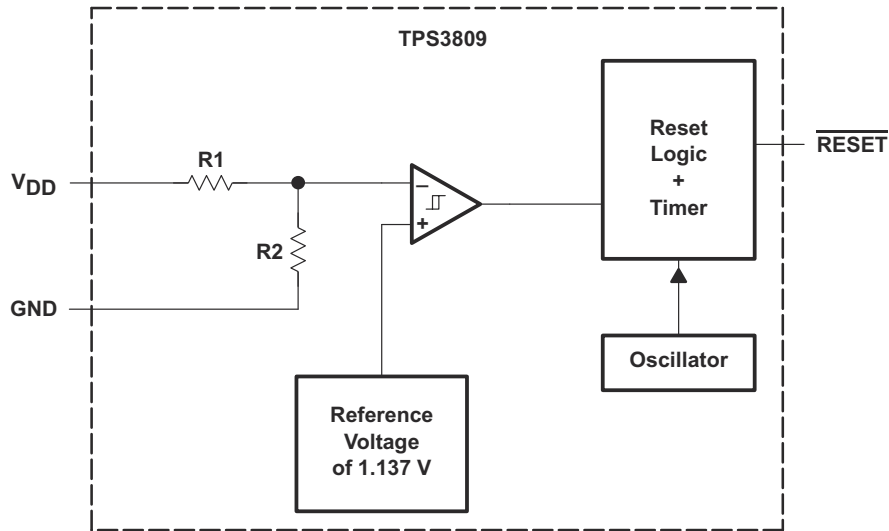


图 7-5. NORMALIZED INPUT THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE AT V_{DD}=2.3V

8 Detailed Description



9 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3809I50DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809J25DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809K33DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVRG4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS3809K33DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809L30DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TPS3809 :

- Automotive : [TPS3809-Q1](#)
- Enhanced Product : [TPS3809-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809I50DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809J25DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809J25DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809K33DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809L30DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809L30DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809I50DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809J25DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809J25DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809K33DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809K33DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809L30DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809L30DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0

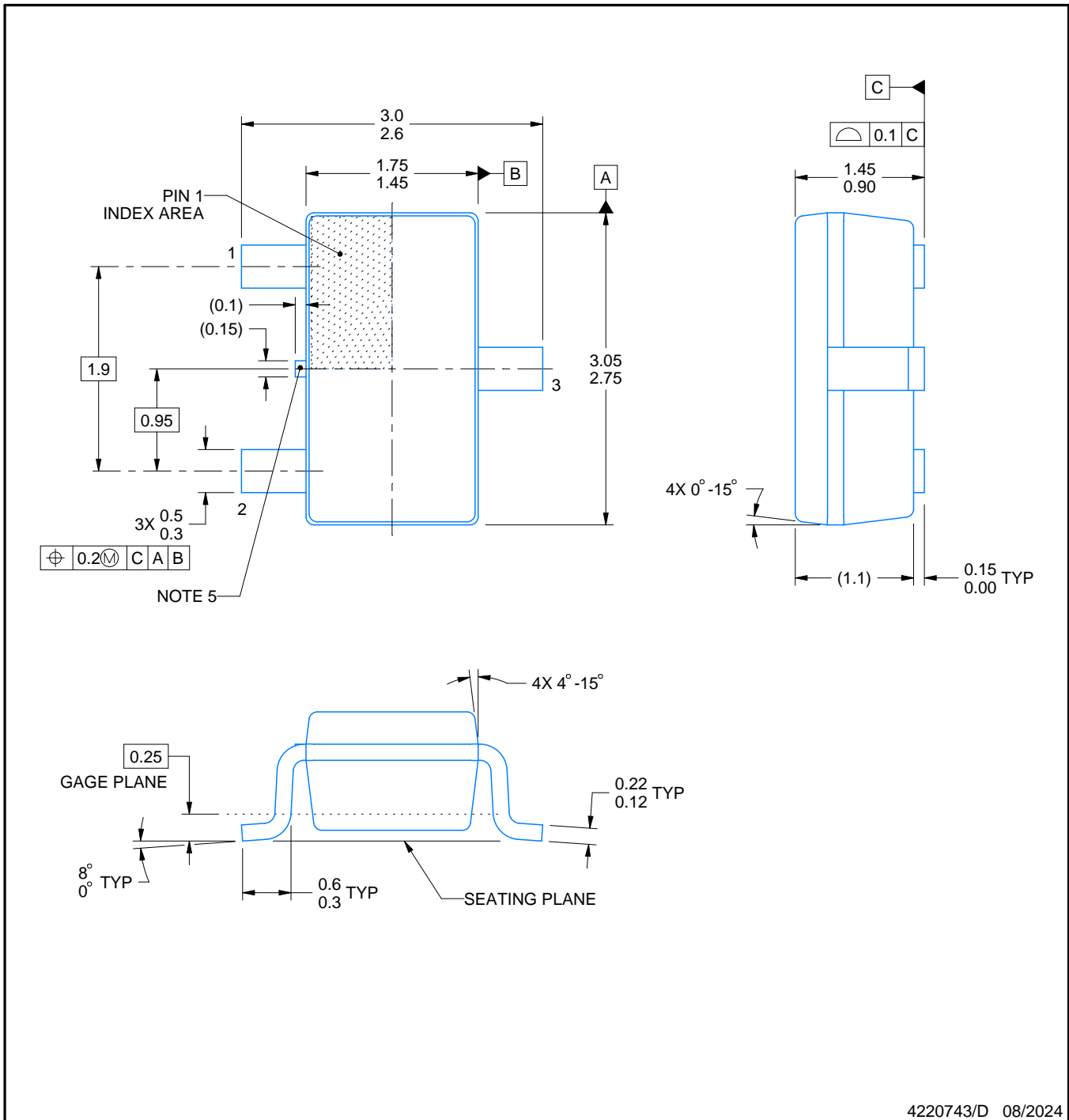
DBV0003A



PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



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NOTES:

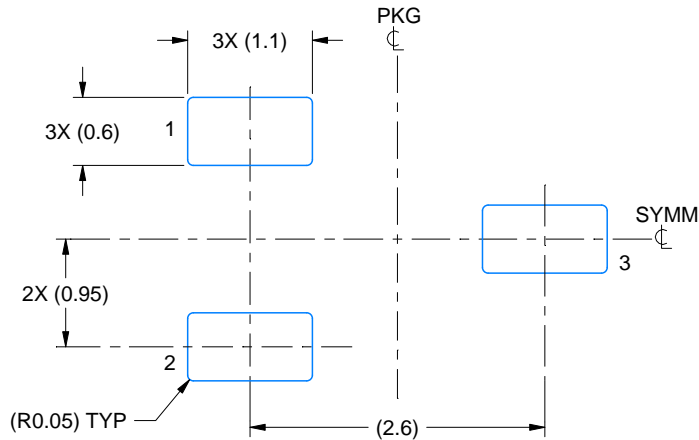
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

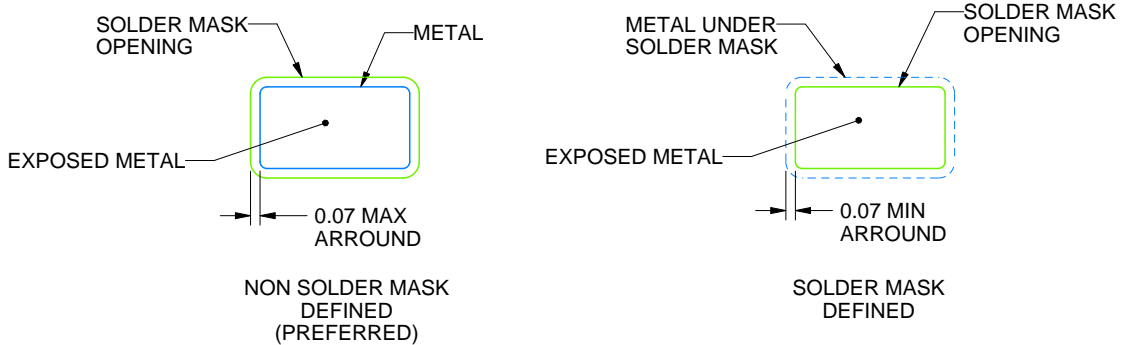
DBV0003A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

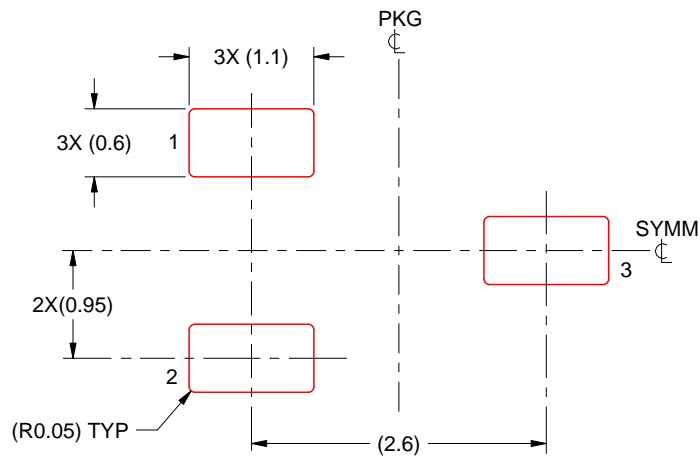
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0003A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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